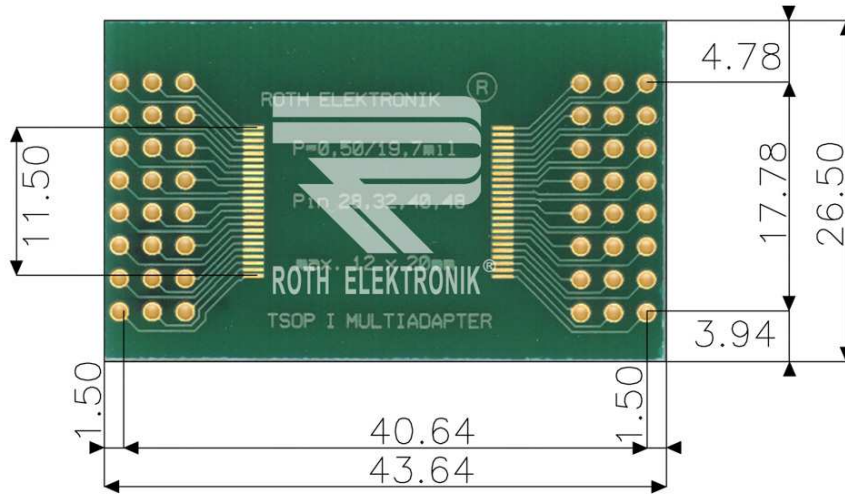




RE900-02

- Epoxy fibre-glass FR4 1.50 mm
 - Double-sided 35 µm Cu
 - Plated through holes (PTH)
 - Surface chem. Ni/Au with solder stop mask
 - Adaption circuit board for TSOP I 28, 32, 40, 48 (0.50 mm)
 - Hole diameter 1.00 mm
 - Gerber data for manufacture of the soldering paste imprint will be provided free of charge on request
 - Size: 26.50 x 43.64 mm
- Modul-No. Type Pitch Pin Size (mm)

RE900-02 TSOP I 0,500 mm 28, 32, 40, 48 12.00 x 20.00

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